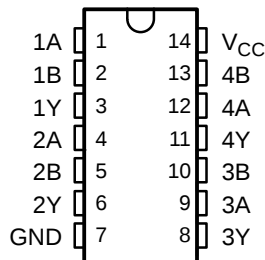


FEATURES

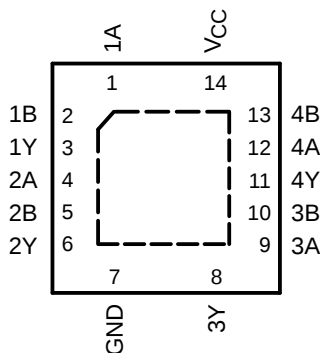
- Operate From 1.65 V to 3.6 V
- Specified From -40°C to 85°C , -40°C to 125°C , and -55°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.6 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}\text{C}$

- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}\text{C}$
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

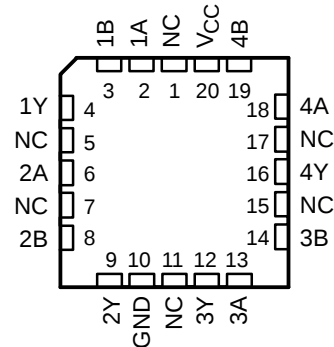
SN54LVC86A . . . J OR W PACKAGE
SN74LVC86A . . . D, DB, NS, OR PW PACKAGE
(TOP VIEW)



SN74LVC86A . . . RGY PACKAGE
(TOP VIEW)



SN54LVC86A . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

DESCRIPTION/ORDERING INFORMATION

The SN54LVC86A quadruple 2-input exclusive-OR gate is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC86A quadruple 2-input exclusive-OR gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The 'LVC86A devices perform the Boolean function $Y = A \oplus B$ or $Y = \bar{A}B + A\bar{B}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVC86ARGYR	LC86A
-40°C to 125°C	SOIC – D	Tube of 50	SN74LVC86AD	LVC86A
		Reel of 2500	SN74LVC86ADR	
		Reel of 250	SN74LVC86ADT	
	SOP – NS	Reel of 2000	SN74LVC86ANSR	LVC86A
	SSOP – DB	Reel of 2000	SN74LVC86ADBR	LC86A
	TSSOP – PW	Tube of 90	SN74LVC86APW	LC86A
		Reel of 2000	SN74LVC86APWR	
		Reel of 250	SN74LVC86APWT	
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54LVC86AJ	SNJ54LVC86AJ
	CFP – W	Tube of 150	SNJ54LVC86AW	SNJ54LVC86AW
	LCCC – FK	Tube of 55	SNJ54LVC86AFK	SNJ54LVC86AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

**FUNCTION TABLE
(EACH GATE)**

INPUTS		OUTPUT Y
A	B	
L	L	L
L	H	H
H	L	H
H	H	L

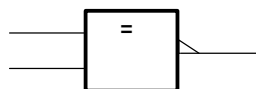
EXCLUSIVE-OR LOGIC

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



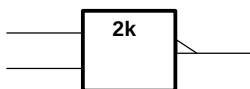
These five equivalent exclusive-OR symbols are valid for an SN74LVC86A gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



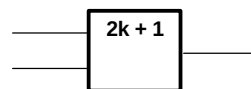
The output is active (low) if all inputs stand at the same logic level (i.e., $A = B$).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	6.5	V
V_I	Input voltage range ⁽²⁾		–0.5	6.5	V
V_O	Output voltage range ⁽²⁾⁽³⁾		–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance	D package ⁽⁴⁾		86	°C/W
		DB package ⁽⁴⁾		96	
		NS package ⁽⁴⁾		76	
		PW package ⁽⁴⁾		113	
		RGY package ⁽⁴⁾		47	
T_{stg}	Storage temperature range		–65	150	°C
P_{tot}	Power dissipation	$T_A = -40^\circ\text{C to } 125^\circ\text{C}^{(5)(6)}$		500	mW

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.
- (5) For the D package: above 70°C, the value of P_{tot} derates linearly with 8 mW/K.
- (6) For the DB, DGV, NS, and PW packages: above 60°C, the value of P_{tot} derates linearly with 5.5 mW/K.

Recommended Operating Conditions⁽¹⁾

			SN54LVC86A		UNIT
			–55 TO 125°C		
			MIN	MAX	
V _{CC}	Supply voltage	Operating	2	3.6	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 2.7 V to 3.6 V	2		V
V _{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
V _I	Input voltage		0	5.5	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2.7 V		–12	mA
		V _{CC} = 3 V		–24	
I _{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
Δt/Δv	Input transition rise or fall rate			9	ns/V

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54LVC86A, SN74LVC86A

QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

SCAS288P–JANUARY 1993–REVISED APRIL 2005

Recommended Operating Conditions⁽¹⁾

			SN74LVC86A						UNIT
			T _A = 25°C		–40 TO 85°C		–40 TO 125°C		
			MIN	MAX	MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		0.65 × V _{CC}		0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		1.7		1.7		
		V _{CC} = 2.7 V to 3.6 V	2		2		2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		0.35 × V _{CC}		0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		0.7		0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		0.8		0.8		
V _I	Input voltage		0	5.5	0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	–4		–4		–4		mA
		V _{CC} = 2.3 V	–8		–8		–8		
		V _{CC} = 2.7 V	–12		–12		–12		
		V _{CC} = 3 V	–24		–24		–24		
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		4		4		mA
		V _{CC} = 2.3 V	8		8		8		
		V _{CC} = 2.7 V	12		12		12		
		V _{CC} = 3 V	24		24		24		
Δt/Δv	Input transition rise or fall rate		9		9		9	ns/V	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	SN54LVC86A			UNIT
				–55 TO 125°C			
				MIN	TYP	MAX	
V _{OH}	I _{OH} = –100 μA		2.7 V to 3.6 V	V _{CC} – 0.2			V
	I _{OH} = –12 mA		2.7 V	2.2			
			3 V	2.4			
	I _{OH} = –24 mA		3 V	2.2			
V _{OL}	I _{OL} = 100 μA		2.7 V to 3.6 V	0.2			V
	I _{OL} = 12 mA		2.7 V	0.4			
	I _{OL} = 24 mA		3 V	0.55			
I _I	V _I = 5.5 V or GND		3.6 V	±5			μA
I _{CC}	V _I = V _{CC} or GND	I _O = 0	3.6 V	10			μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V	500			μA
C _i	V _I = V _{CC} or GND		3.3 V	5 ⁽¹⁾			pF

(1) T_A = 25°C

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	SN74LVC86A						UNIT	
				T _A = 25°C			–40 TO 85°C		–40 TO 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN		MAX
V _{OH}	I _{OH} = –100 μA		1.65 V to 3.6 V	V _{CC} – 0.2			V _{CC} – 0.2		V _{CC} – 0.3		V
	I _{OH} = –4 mA		1.65 V	1.29			1.2		1.05		
	I _{OH} = –8 mA		2.3 V	1.9			1.7		1.55		
	I _{OH} = –12 mA		2.7 V	2.2			2.2		2.05		
			3 V	2.4			2.4		2.25		
	I _{OH} = –24 mA		3 V	2.3			2.2		2		
V _{OL}	I _{OL} = 100 μA		1.65 V to 3.6 V	0.1			0.2		0.3		V
	I _{OL} = 4 mA		1.65 V	0.24			0.45		0.6		
	I _{OL} = 8 mA		2.3 V	0.3			0.7		0.75		
	I _{OL} = 12 mA		2.7 V	0.4			0.4		0.6		
	I _{OL} = 24 mA		3 V	0.55			0.55		0.8		
I _I	V _I = 5.5 V or GND		3.6 V	±1			±5		±20		μA
I _{CC}	V _I = V _{CC} or GND	I _O = 0	3.6 V	1			10		40		μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V	500			500		5000		μA
C _i	V _I = V _{CC} or GND		3.3 V	5							pF

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN54LVC86A		UNIT
				–55 TO 125°C		
				MIN	MAX	
t _{pd}	A	Y	2.7 V	5.6		ns
			3.3 V ± 0.3 V	1	4.6	

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

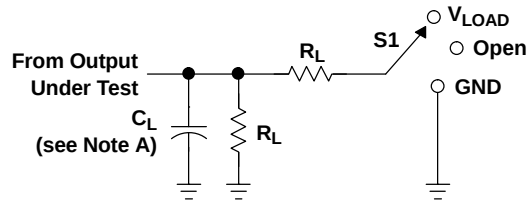
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN74LVC86A							UNIT
				T _A = 25°C			–40 TO 85°C		–40 TO 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	1.8 V ± 0.15 V	1	4.1	9.4	1	9.9	1	11.4	ns
			2.5 V ± 0.2 V	1	2.9	7.1	1	7.6	1	9.7	
			2.7 V	1	2.8	5.4	1	5.6	1	7.1	
			3.3 V ± 0.3 V	1	2.5	4.4	1	4.6	1	5.8	
t _{sk(o)}			3.3 V ± 0.3 V				1		1.5		ns

Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V _{CC}	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	f = 10 MHz	1.8 V	6.5	pF
			2.5 V	7.5	
			3.3 V	8.5	

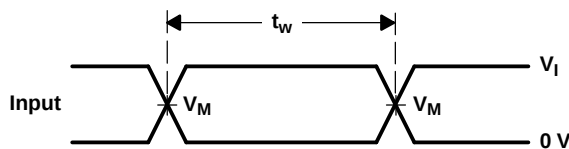
PARAMETER MEASUREMENT INFORMATION



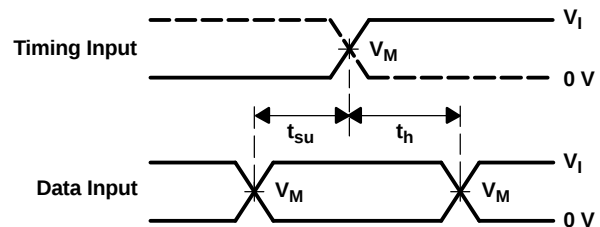
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

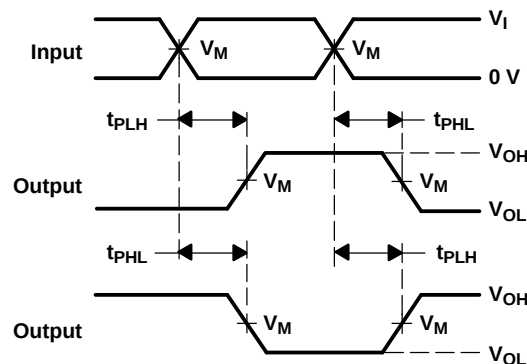
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



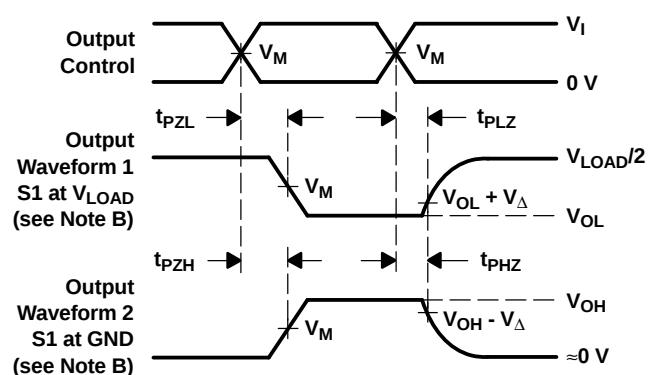
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9761901Q2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9761901Q2A SNJ54LVC 86AFK	Samples
5962-9761901QDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9761901QD A SNJ54LVC86AW	Samples
SN74LVC86AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC86A	Samples
SN74LVC86ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC86A	Samples
SN74LVC86ADG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC86A	Samples
SN74LVC86ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC86A	Samples
SN74LVC86ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC86A	Samples
SN74LVC86ADT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC86A	Samples
SN74LVC86ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC86A	Samples
SN74LVC86APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC86A	Samples
SN74LVC86APWE4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC86A	Samples
SN74LVC86APWG4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC86A	Samples
SN74LVC86APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC86A	Samples
SN74LVC86APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC86A	Samples
SN74LVC86ARGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC86A	Samples
SN74LVC86ARGYRG4	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC86A	Samples
SNJ54LVC86AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9761901Q2A SNJ54LVC 86AFK	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LVC86AW	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9761901QD A SNJ54LVC86AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

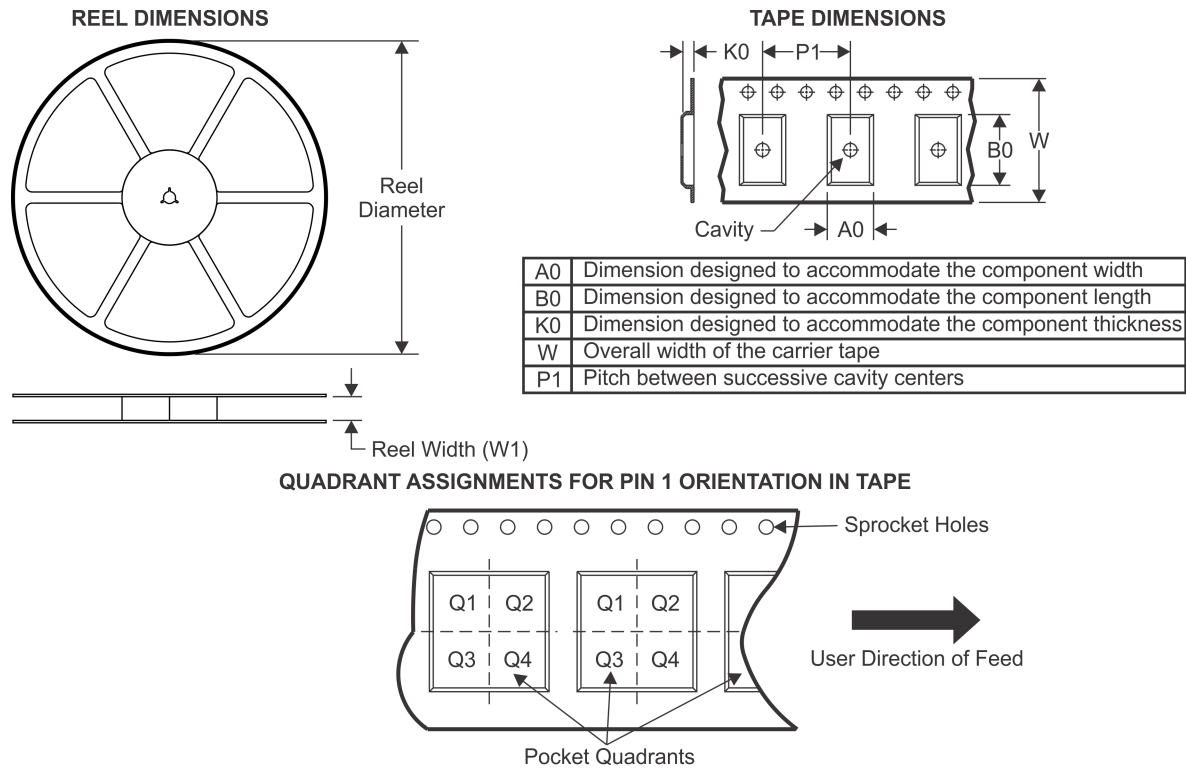
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVC86A, SN74LVC86A :

- Catalog: [SN74LVC86A](#)
- Automotive: [SN74LVC86A-Q1](#), [SN74LVC86A-Q1](#)
- Enhanced Product: [SN74LVC86A-EP](#), [SN74LVC86A-EP](#)
- Military: [SN54LVC86A](#)

NOTE: Qualified Version Definitions:

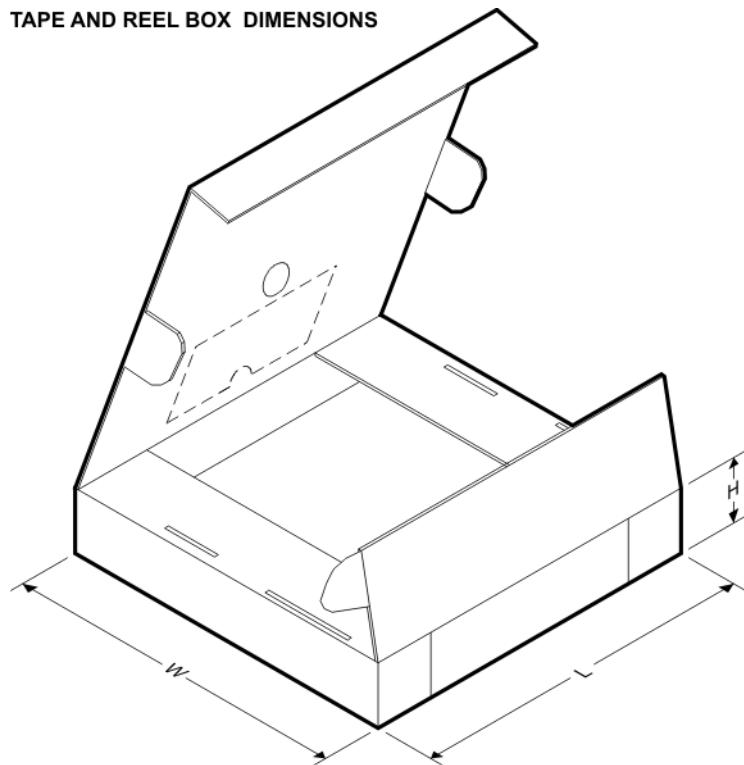
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC86ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVC86ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC86ADT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC86ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVC86APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC86ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

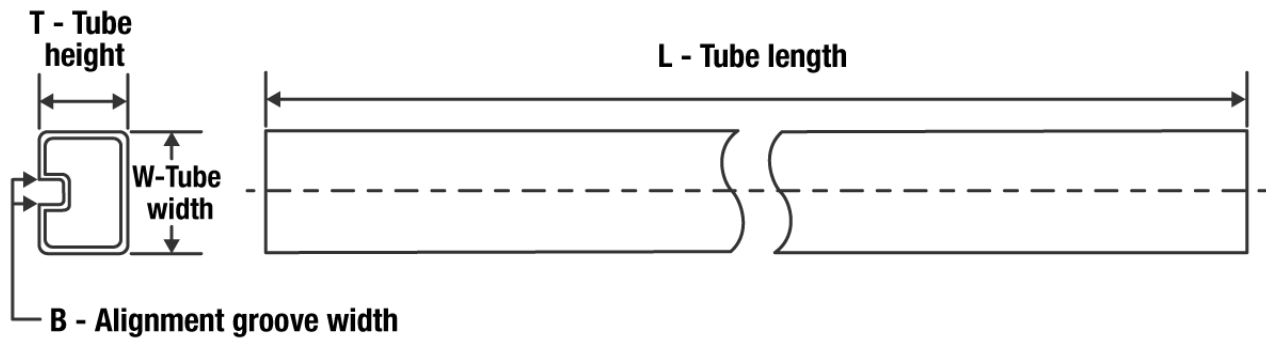
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC86ADBR	SSOP	DB	14	2000	853.0	449.0	35.0
SN74LVC86ADR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LVC86ADT	SOIC	D	14	250	210.0	185.0	35.0
SN74LVC86ANSR	SO	NS	14	2000	853.0	449.0	35.0
SN74LVC86APWR	TSSOP	PW	14	2000	853.0	449.0	35.0
SN74LVC86ARGYR	VQFN	RGY	14	3000	853.0	449.0	35.0

TUBE

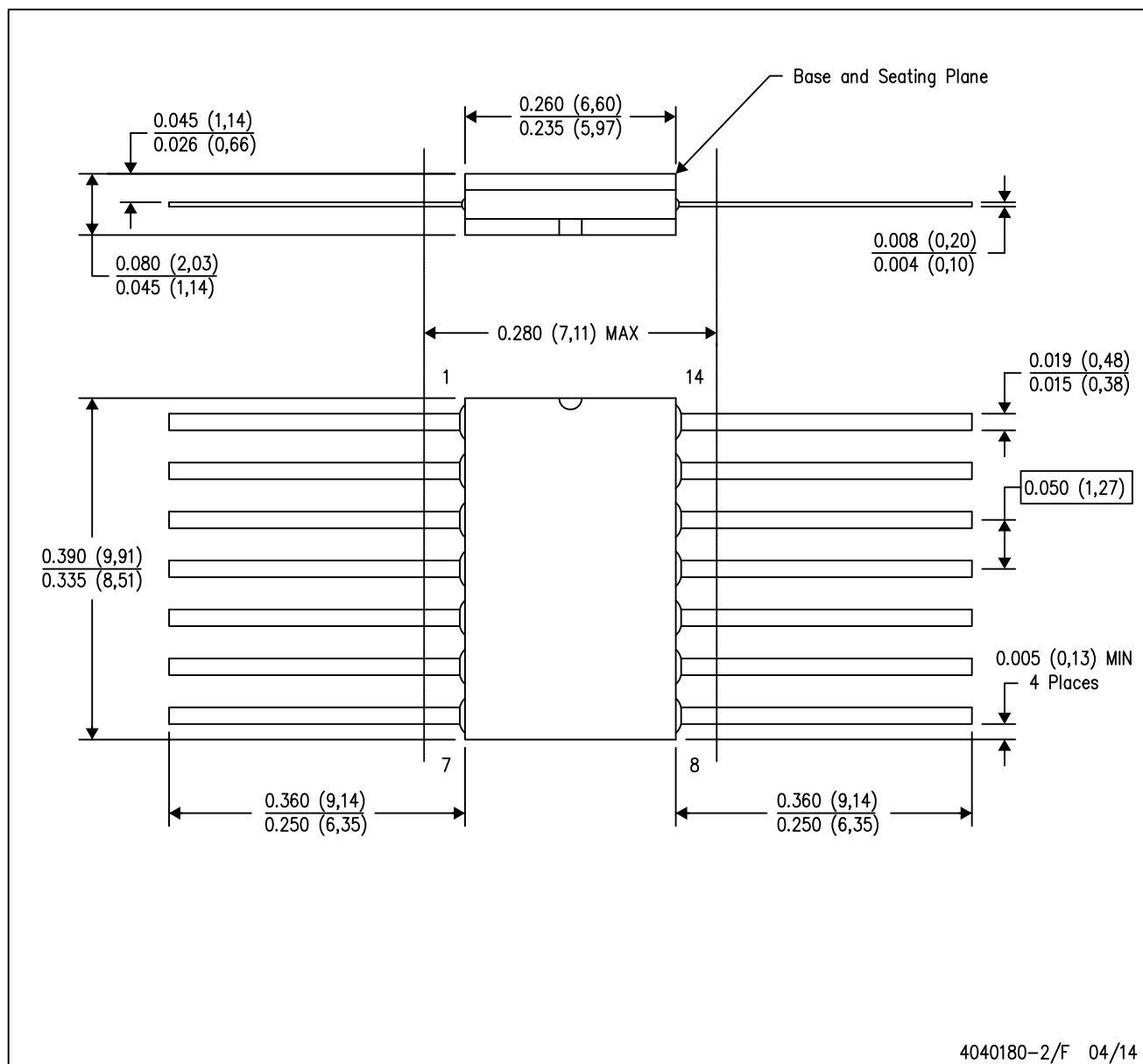


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9761901Q2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LVC86AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVC86ADG4	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVC86APW	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74LVC86APWE4	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74LVC86APWG4	PW	TSSOP	14	90	530	10.2	3600	3.5
SNJ54LVC86AFK	FK	LCCC	20	1	506.98	12.06	2030	NA

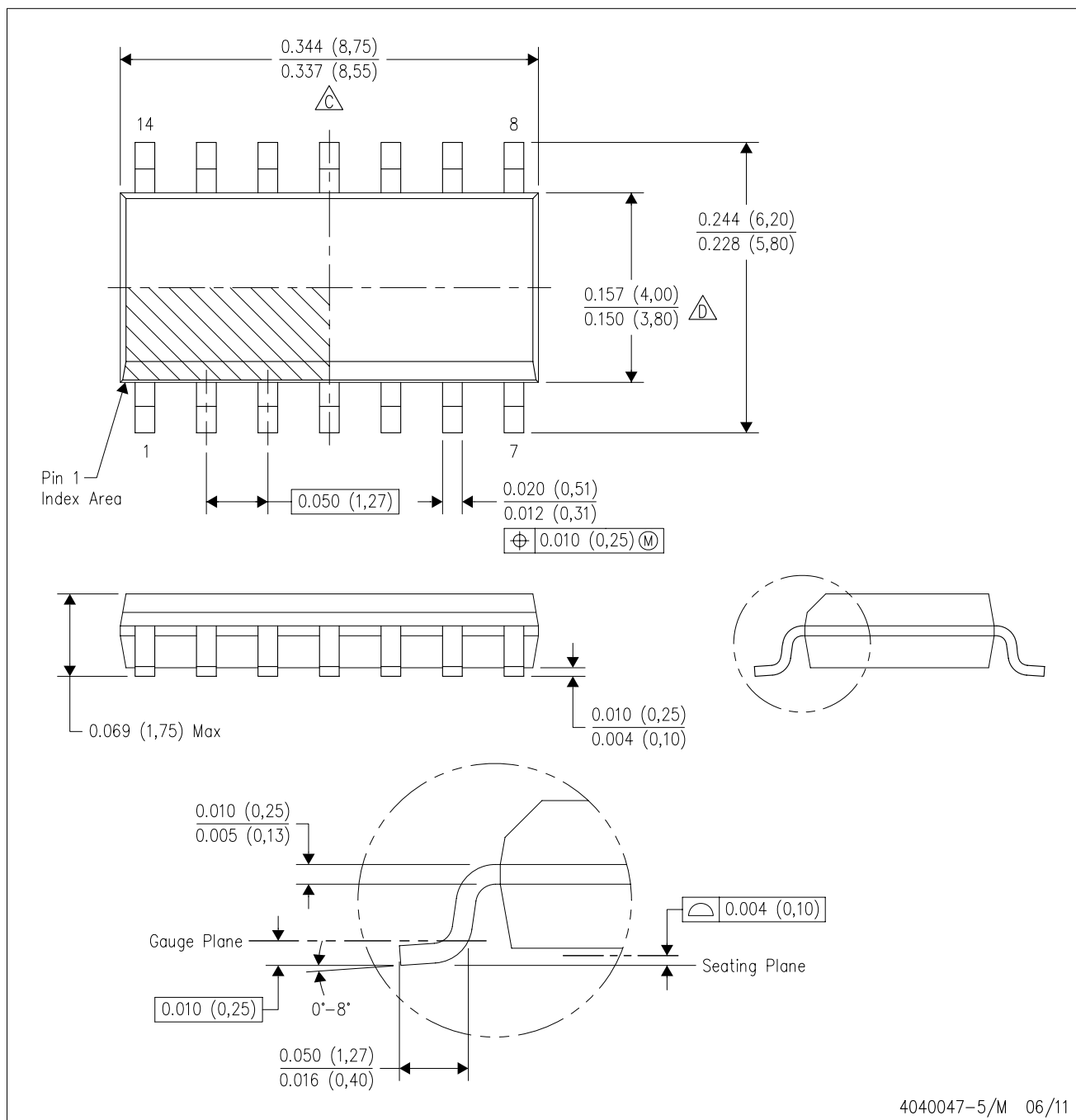
W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



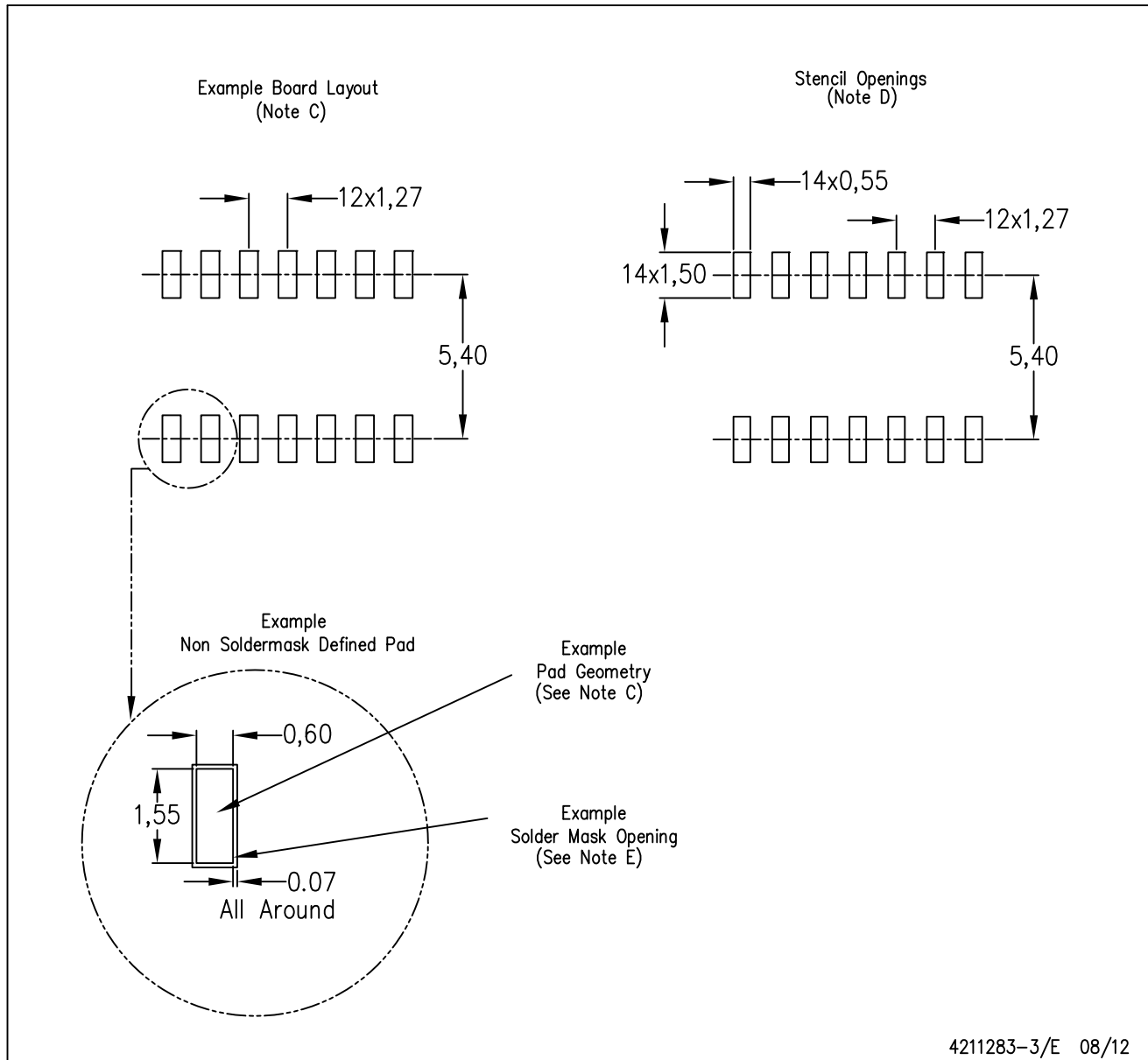
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

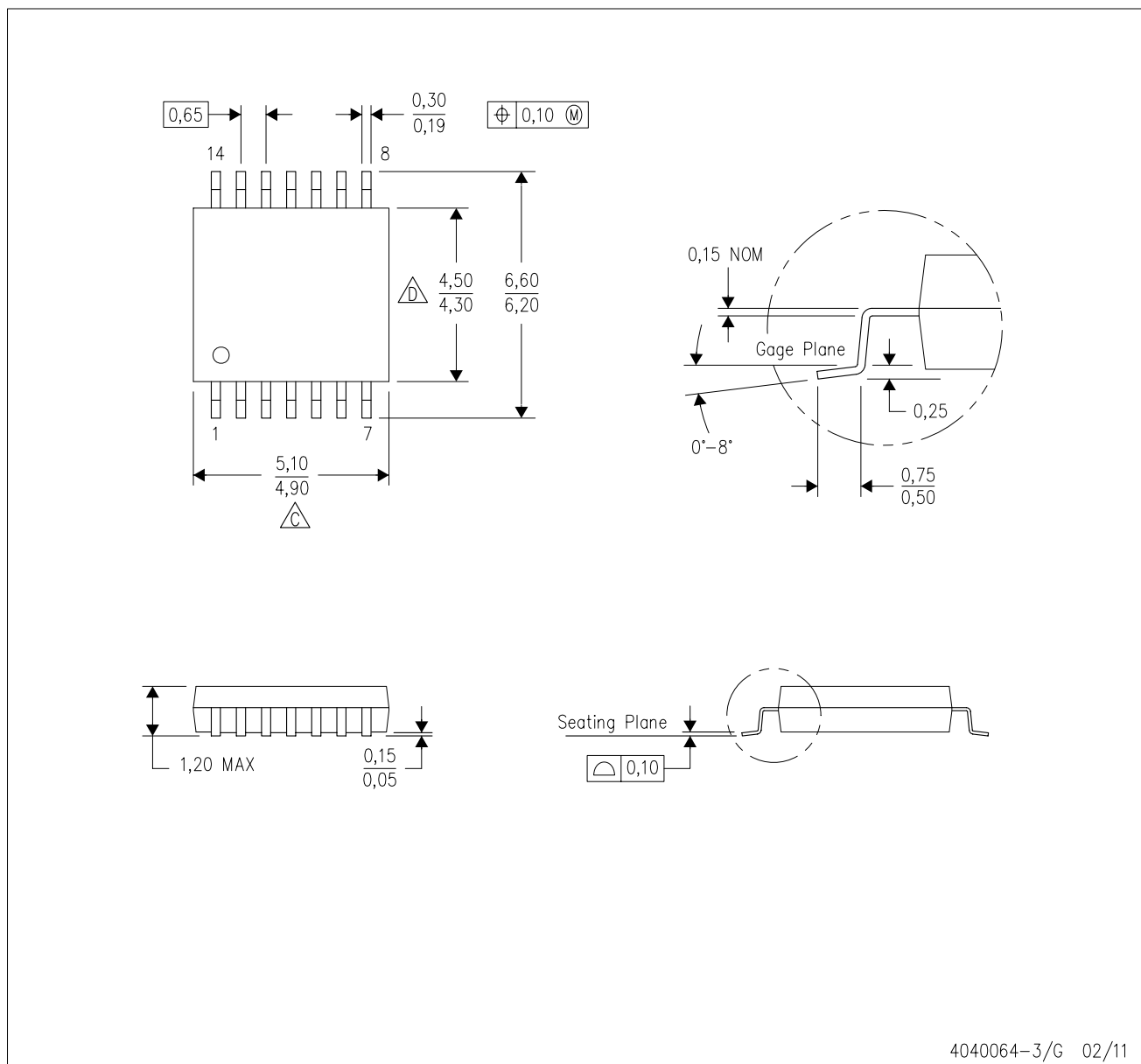
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

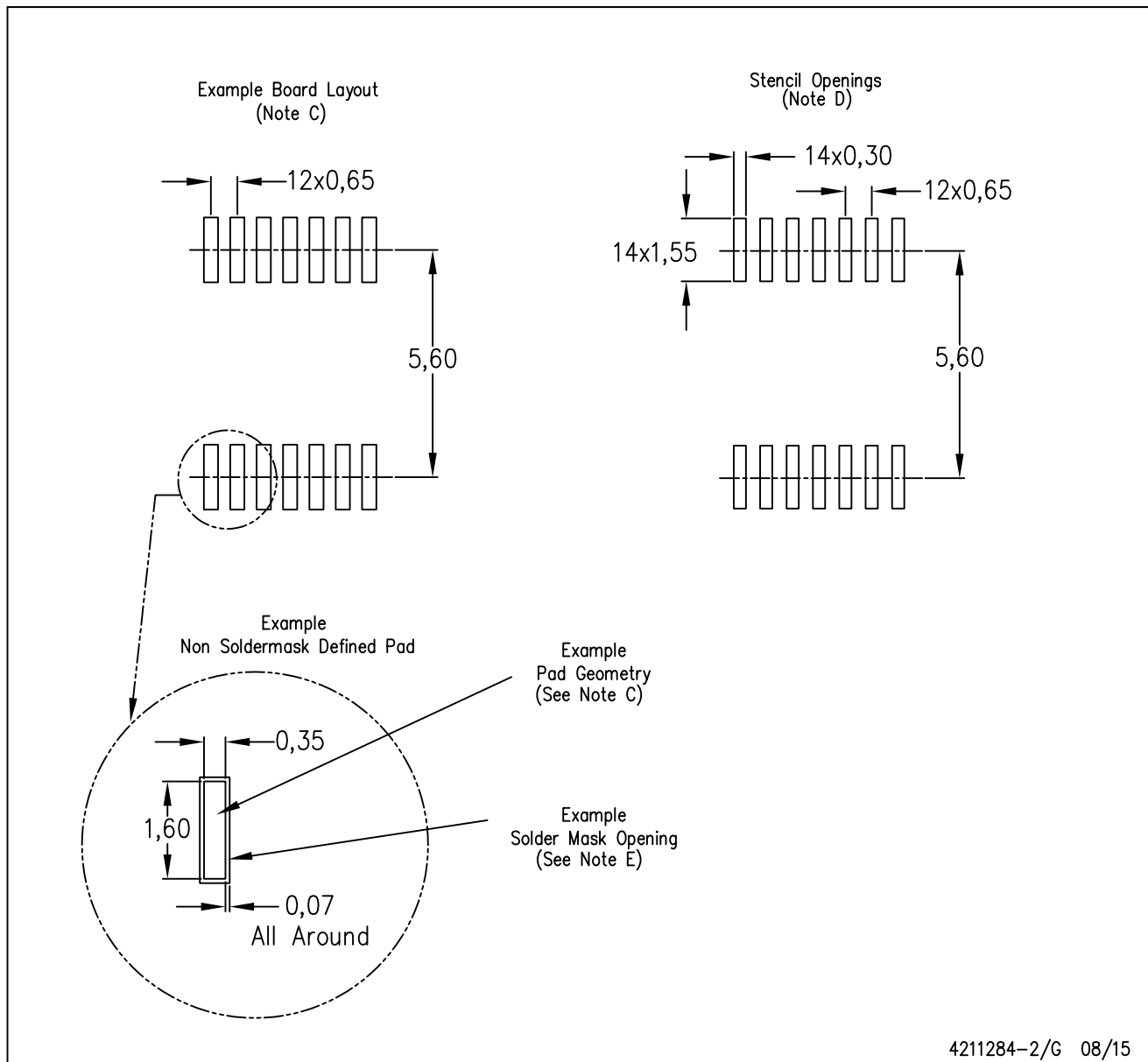
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



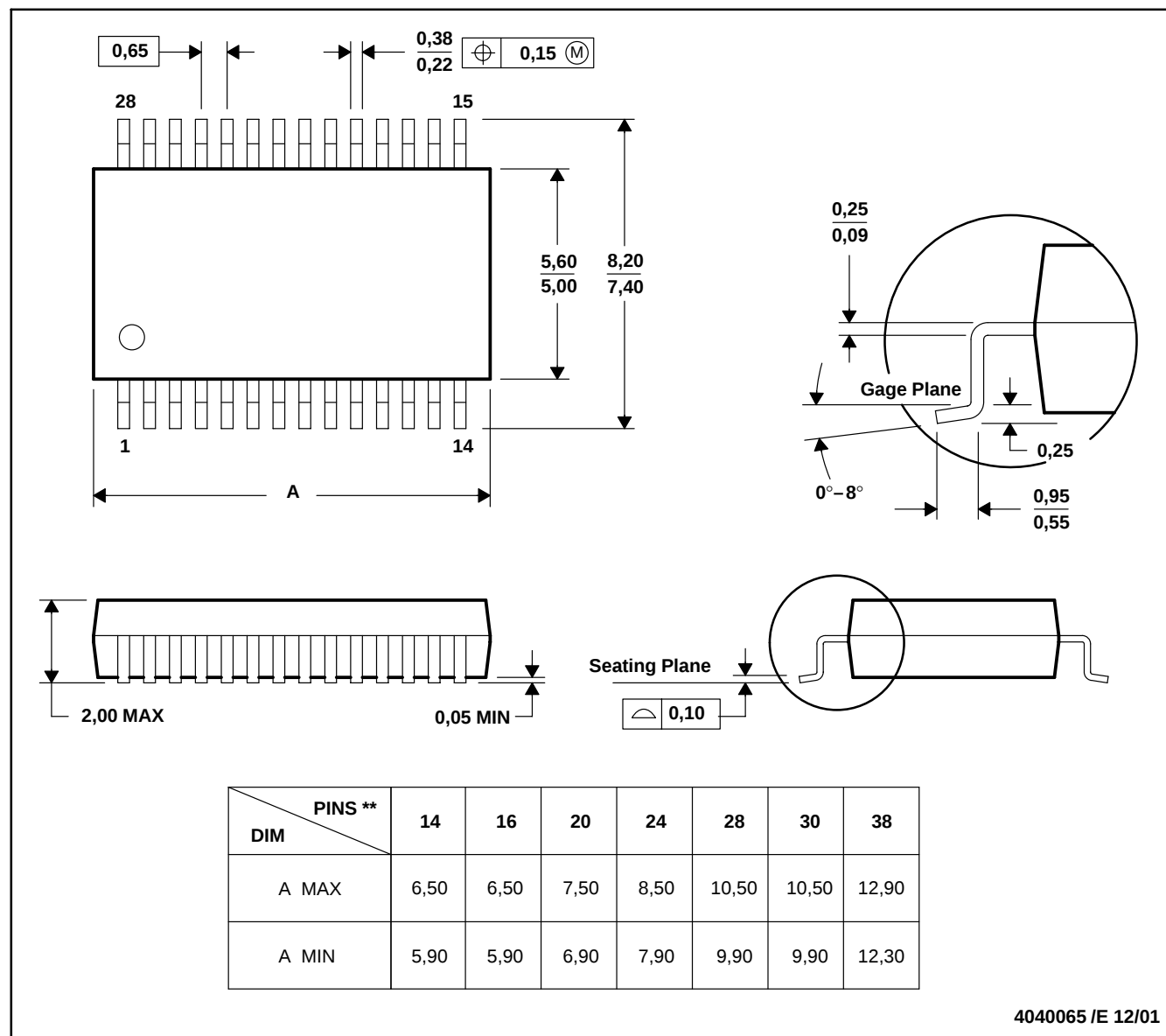
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN

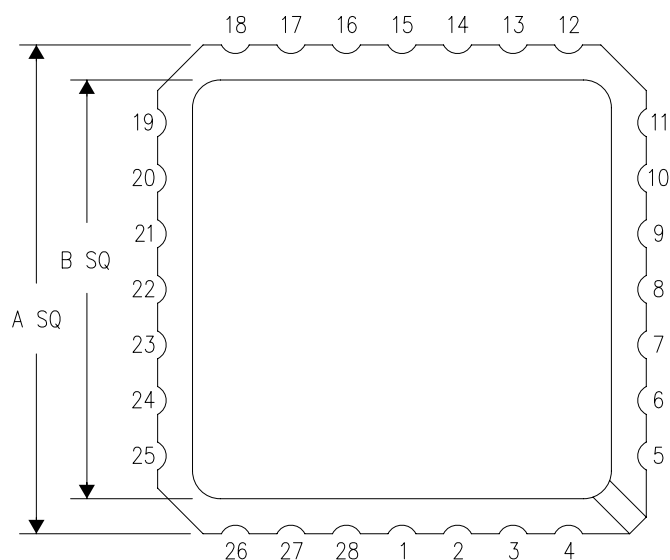


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

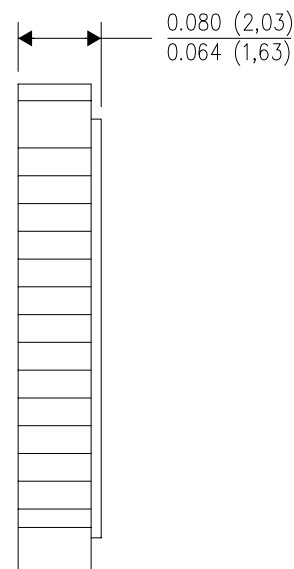
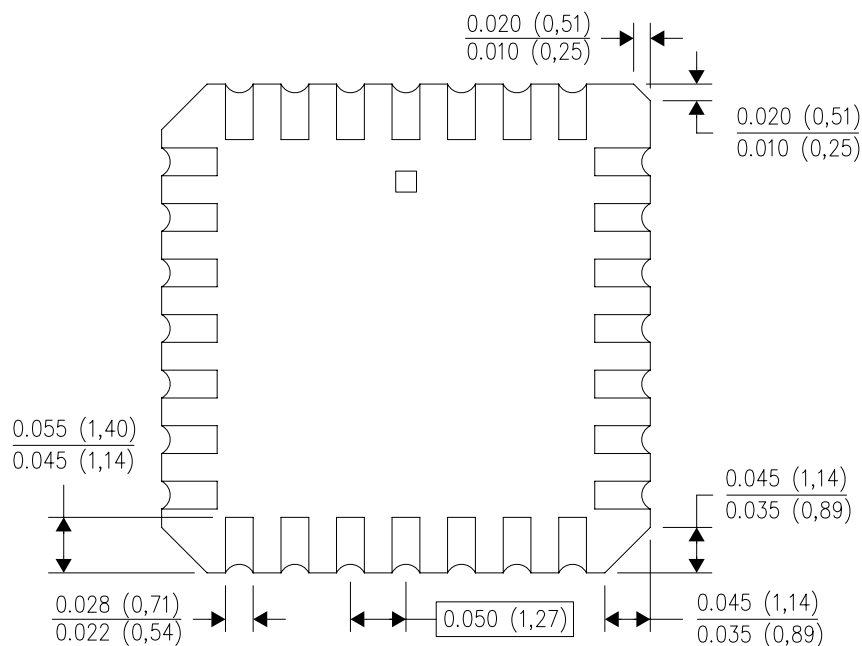
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

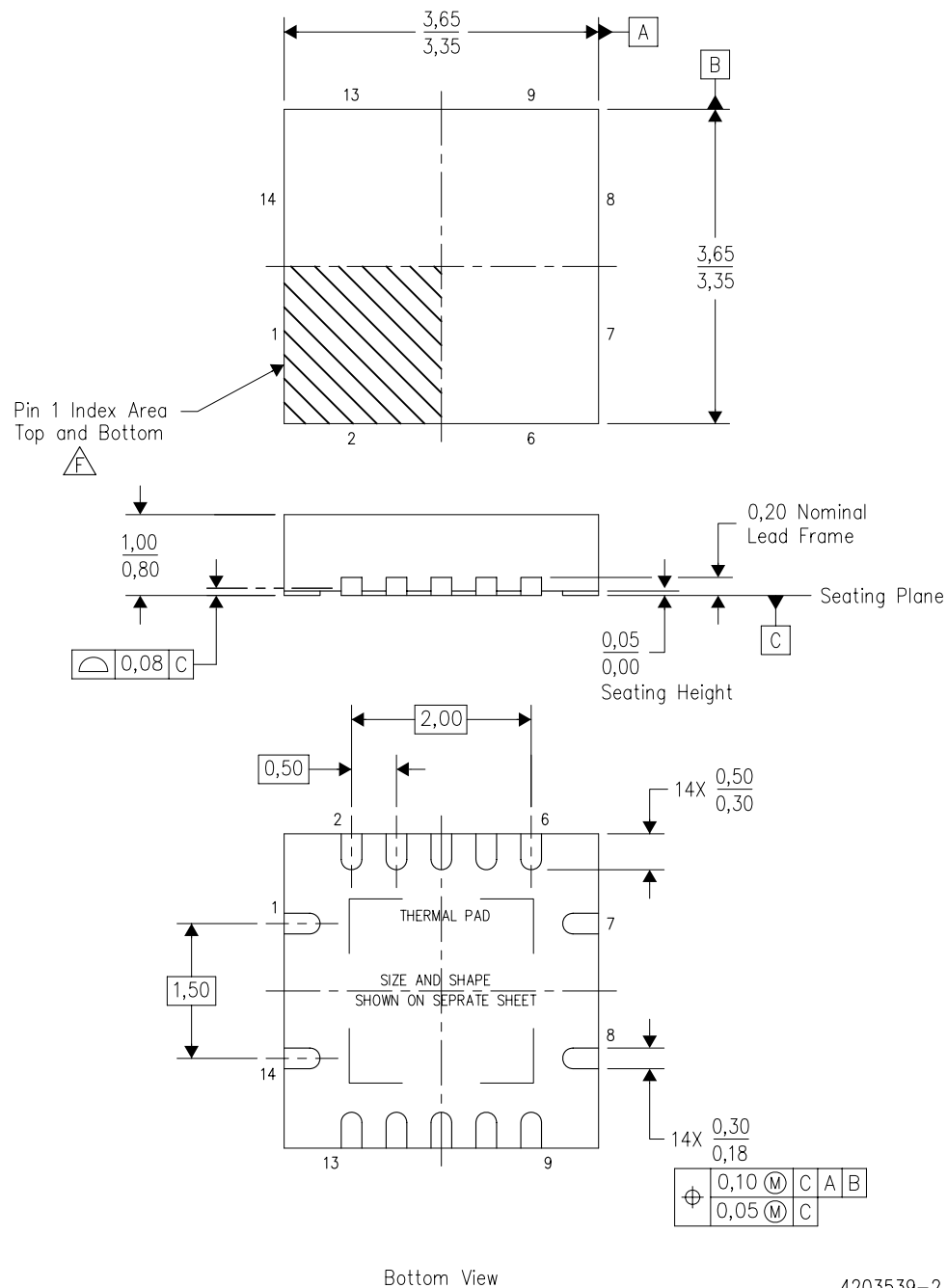


4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

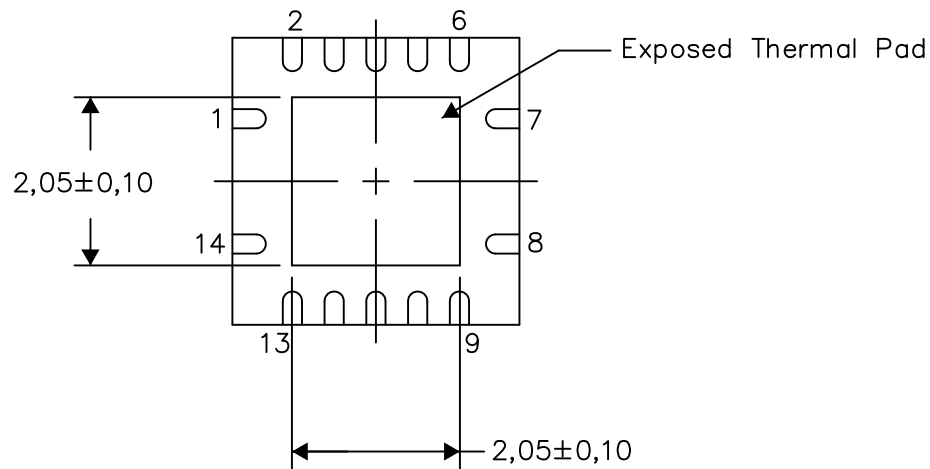
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

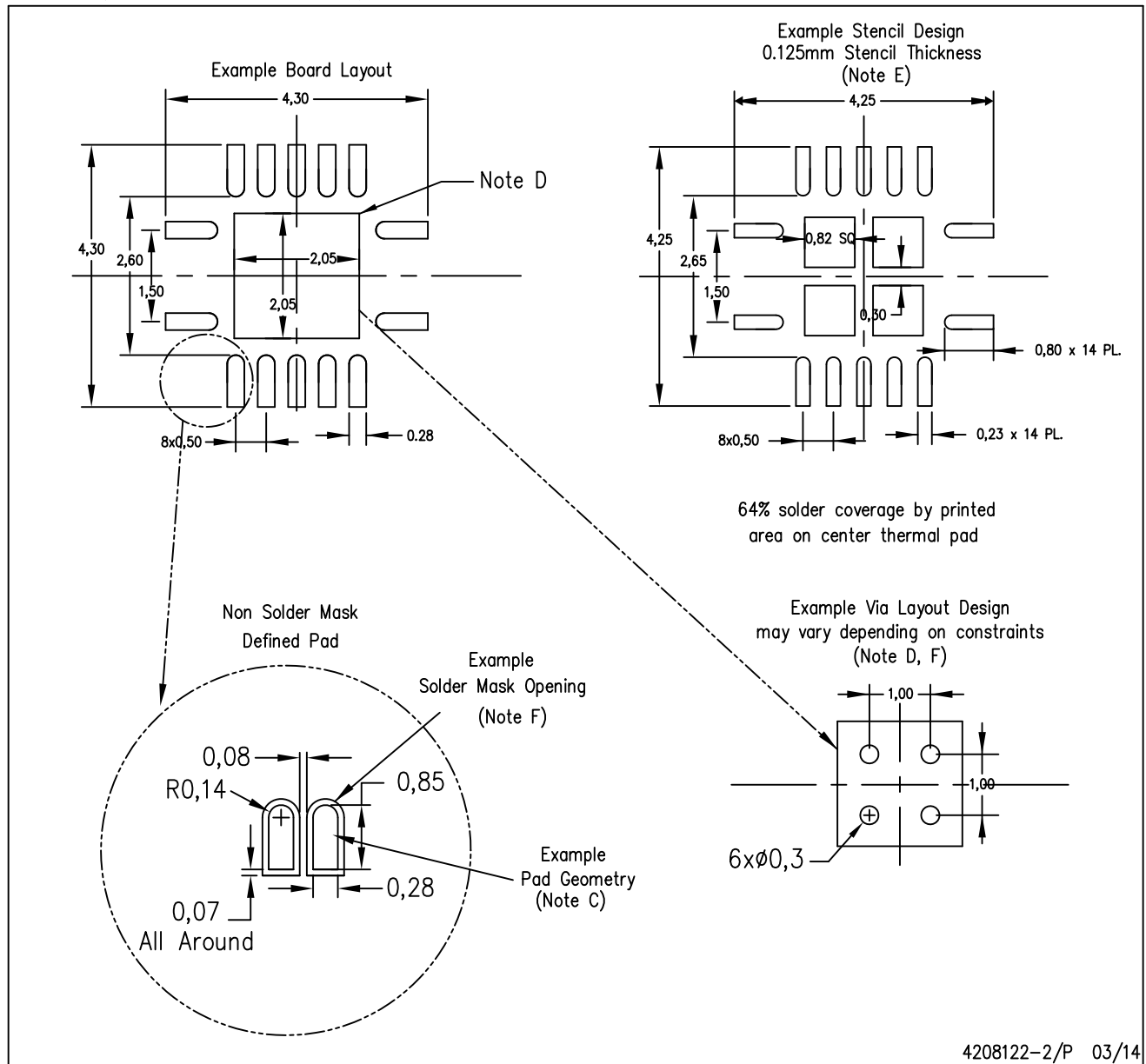
Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-2/P 03/14

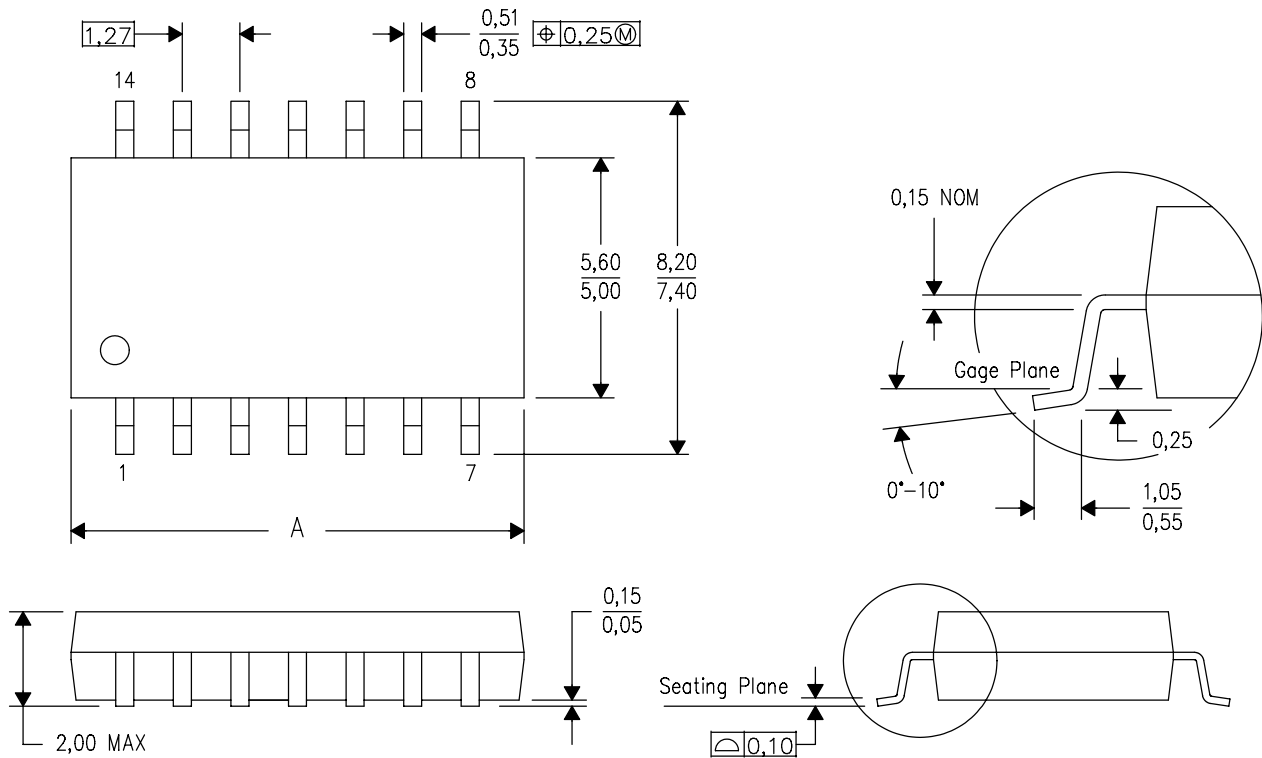
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2022, Texas Instruments Incorporated